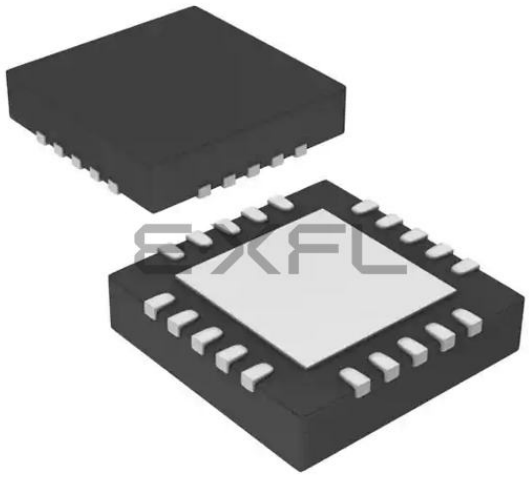


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-VFQFN Exposed Pad
Supplier Device Package	20-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1509-e-ml

TABLE 1-2: PIC16(L)F1508/9 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0/C1IN+/DAC1OUT1/ ICSPDAT/ICDDAT	RA0	TTL	CMOS	General purpose I/O.
	AN0	AN	—	ADC Channel input.
	C1IN+	AN	—	Comparator positive input.
	DAC1OUT1	—	AN	Digital-to-Analog Converter output.
	ICSPDAT	ST	CMOS	ICSP™ Data I/O.
	ICDDAT	ST	CMOS	In-Circuit Debug data.
RA1/AN1/CLC4IN1/VREF+/ C1IN0-/C2IN0-/ICSPCLK/ ICDCLK	RA1	TTL	CMOS	General purpose I/O.
	AN1	AN	—	ADC Channel input.
	CLC4IN1	ST	—	Configurable Logic Cell source input.
	VREF+	AN	—	ADC Positive Voltage Reference input.
	C1IN0-	AN	—	Comparator negative input.
	C2IN0-	AN	—	Comparator negative input.
	ICSPCLK	ST	—	ICSP Programming Clock.
	ICDCLK	ST	—	In-Circuit Debug Clock.
RA2/AN2/C1OUT/DAC1OUT2/ T0CKI/INT/PWM3/CLC1/ CWG1FLT	RA2	ST	CMOS	General purpose I/O.
	AN2	AN	—	ADC Channel input.
	C1OUT	—	CMOS	Comparator output.
	DAC1OUT2	—	AN	Digital-to-Analog Converter output.
	T0CKI	ST	—	Timer0 clock input.
	INT	ST	—	External interrupt.
	PWM3	—	CMOS	PWM output.
	CLC1	—	CMOS	Configurable Logic Cell source output.
	CWG1FLT	ST	—	Complementary Waveform Generator Fault input.
RA3/CLC1IN0/VPP/T1G(1)/SS(1)/ MCLR	RA3	TTL	—	General purpose input with IOC and WPU.
	CLC1IN0	ST	—	Configurable Logic Cell source input.
	VPP	HV	—	Programming voltage.
	T1G	ST	—	Timer1 Gate input.
	SS	ST	—	Slave Select input.
	MCLR	ST	—	Master Clear with internal pull-up.
RA4/AN3/SOSCO/ CLKOUT/T1G	RA4	TTL	CMOS	General purpose I/O.
	AN3	AN	—	ADC Channel input.
	SOSCO	XTAL	XTAL	Secondary Oscillator Connection.
	CLKOUT	—	CMOS	FOSC/4 output.
	T1G	ST	—	Timer1 Gate input.
RA5/CLKIN/T1CKI/NCO1CLK/ SOSCI	RA5	TTL	CMOS	General purpose I/O.
	CLKIN	CMOS	—	External clock input (EC mode).
	T1CKI	ST	—	Timer1 clock input.
	NCO1CLK	ST	—	Numerically Controlled Oscillator Clock source input.
	SOSCI	XTAL	XTAL	Secondary Oscillator Connection.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open-Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C = Schmitt Trigger input with I^2C levels
HV = High Voltage XTAL = Crystal

Note 1: Alternate pin function selected with the APFCON (Register 11-1) register.

TABLE 3-5: PIC16(L)F1508/9 MEMORY MAP, BANK 8-23

BANK 8	BANK 9	BANK 10	BANK 11	BANK 12	BANK 13	BANK 14	BANK 15
400h Core Registers (Table 3-2) 40Bh	480h Core Registers (Table 3-2) 48Bh	500h Core Registers (Table 3-2) 50Bh	580h Core Registers (Table 3-2) 58Bh	600h Core Registers (Table 3-2) 60Bh	680h Core Registers (Table 3-2) 68Bh	700h Core Registers (Table 3-2) 70Bh	780h Core Registers (Table 3-2) 78Bh
40Ch —	48Ch —	50Ch —	58Ch —	60Ch —	68Ch —	70Ch —	78Ch —
40Dh —	48Dh —	50Dh —	58Dh —	60Dh —	68Dh —	70Dh —	78Dh —
40Eh —	48Eh —	50Eh —	58Eh —	60Eh —	68Eh —	70Eh —	78Eh —
40Fh —	48Fh —	50Fh —	58Fh —	60Fh —	68Fh —	70Fh —	78Fh —
410h —	490h —	510h —	590h —	610h —	690h —	710h —	790h —
411h —	491h —	511h —	591h —	611h PWM1DCL	691h CWG1DBR	711h —	791h —
412h —	492h —	512h —	592h —	612h PWM1DCH	692h CWG1DBF	712h —	792h —
413h —	493h —	513h —	593h —	613h PWM1CON	693h CWG1CON0	713h —	793h —
414h —	494h —	514h —	594h —	614h PWM2DCL	694h CWG1CON1	714h —	794h —
415h —	495h —	515h —	595h —	615h PWM2DCH	695h CWG1CON2	715h —	795h —
416h —	496h —	516h —	596h —	616h PWM2CON	696h —	716h —	796h —
417h —	497h —	517h —	597h —	617h PWM3DCL	697h —	717h —	797h —
418h —	498h NCO1ACCL	518h —	598h —	618h PWM3DCH	698h —	718h —	798h —
419h —	499h NCO1ACCH	519h —	599h —	619h PWM3CON	699h —	719h —	799h —
41Ah —	49Ah NCO1ACCU	51Ah —	59Ah —	61Ah PWM4DCL	69Ah —	71Ah —	79Ah —
41Bh —	49Bh NCO1INCL	51Bh —	59Bh —	61Bh PWM4DCH	69Bh —	71Bh —	79Bh —
41Ch —	49Ch NCO1INCH	51Ch —	59Ch —	61Ch PWM4CON	69Ch —	71Ch —	79Ch —
41Dh —	49Dh —	51Dh —	59Dh —	61Dh —	69Dh —	71Dh —	79Dh —
41Eh —	49Eh NCO1CON	51Eh —	59Eh —	61Eh —	69Eh —	71Eh —	79Eh —
41Fh —	49Fh NCO1CLK	51Fh —	59Fh —	61Fh —	69Fh —	71Fh —	79Fh —
420h Unimplemented Read as '0' 46Fh	4A0h Unimplemented Read as '0' 4EFh	520h Unimplemented Read as '0' 56Fh	5A0h Unimplemented Read as '0' 5EFh	620h Unimplemented Read as '0' 66Fh	6A0h Unimplemented Read as '0' 6EFh	720h Unimplemented Read as '0' 76Fh	7A0h Unimplemented Read as '0' 7EFh
470h Accesses 70h – 7Fh 47Fh	4F0h Accesses 70h – 7Fh 4FFh	570h Accesses 70h – 7Fh 57Fh	5F0h Accesses 70h – 7Fh 5FFh	670h Accesses 70h – 7Fh 67Fh	6F0h Accesses 70h – 7Fh 6FFh	770h Accesses 70h – 7Fh 77Fh	7F0h Accesses 70h – 7Fh 7FFh

BANK 16	BANK 17	BANK 18	BANK 19	BANK 20	BANK 21	BANK 22	BANK 23
800h Core Registers (Table 3-2) 80Bh	880h Core Registers (Table 3-2) 88Bh	900h Core Registers (Table 3-2) 90Bh	980h Core Registers (Table 3-2) 98Bh	A00h Core Registers (Table 3-2) A0Bh	A80h Core Registers (Table 3-2) A8Bh	B00h Core Registers (Table 3-2) B0Bh	B80h Core Registers (Table 3-2) B8Bh
80Ch Unimplemented Read as '0' 86Fh	88Ch Unimplemented Read as '0' 8EFh	90Ch Unimplemented Read as '0' 96Fh	98Ch Unimplemented Read as '0' 9EFh	A0Ch Unimplemented Read as '0' A6Fh	A8Ch Unimplemented Read as '0' AEFh	B0Ch Unimplemented Read as '0' B6Fh	B8Ch Unimplemented Read as '0' BEFh
870h Accesses 70h – 7Fh 87Fh	8F0h Accesses 70h – 7Fh 8FFh	970h Accesses 70h – 7Fh 97Fh	9F0h Accesses 70h – 7Fh 9FFh	A70h Accesses 70h – 7Fh A7Fh	AF0h Accesses 70h – 7Fh AFFh	B70h Accesses 70h – 7Fh B7Fh	BF0h Accesses 70h – 7Fh BFFh

Legend: = Unimplemented data memory locations, read as '0'.

4.2 Register Definitions: Configuration Words

REGISTER 4-1: CONFIG1: CONFIGURATION WORD 1

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1
FCMEN(1)	IESO(1)	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>(2)		—
bit 13					bit 8

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
$\overline{\text{CP}}$(3)	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		FOSC<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **FCMEN:** Fail-Safe Clock Monitor Enable bit
1 = Fail-Safe Clock Monitor is enabled(1)
0 = Fail-Safe Clock Monitor is disabled

bit 12 **IESO:** Internal External Switchover bit(1)
1 = Internal/External Switchover (Two-Speed Start-up) mode is enabled
0 = Internal/External Switchover mode is disabled

bit 11 **$\overline{\text{CLKOUTEN}}$:** Clock Out Enable bit
1 = CLKOUT function is disabled. I/O function on the CLKOUT pin
0 = CLKOUT function is enabled on the CLKOUT pin

bit 10-9 **BOREN<1:0>:** Brown-Out Reset Enable bits(2)
11 = BOR enabled
10 = BOR enabled during operation and disabled in Sleep
01 = BOR controlled by SBOREN bit of the BORCON register
00 = BOR disabled

bit 8 **Unimplemented:** Read as '1'

bit 7 **$\overline{\text{CP}}$:** Code Protection bit(3)
1 = Program memory code protection is disabled
0 = Program memory code protection is enabled

bit 6 **MCLRE:** $\overline{\text{MCLR}}$/V_{PP} Pin Function Select bit
If LVP bit = 1:
This bit is ignored.
If LVP bit = 0:
1 = $\overline{\text{MCLR}}$/V_{PP} pin function is $\overline{\text{MCLR}}$; Weak pull-up enabled.
0 = $\overline{\text{MCLR}}$/V_{PP} pin function is digital input; $\overline{\text{MCLR}}$ internally disabled; Weak pull-up under control of WPUA3 bit.

bit 5 **$\overline{\text{PWRTE}}$:** Power-Up Timer Enable bit
1 = PWRT disabled
0 = PWRT enabled

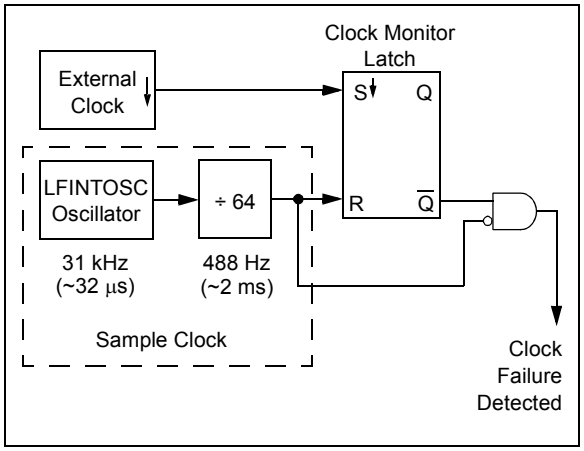
bit 4-3 **WDTE<1:0>:** Watchdog Timer Enable bits
11 = WDT enabled
10 = WDT enabled while running and disabled in Sleep
01 = WDT controlled by the SWDTEN bit in the WDTCON register
00 = WDT disabled

5.5 Fail-Safe Clock Monitor

The Fail-Safe Clock Monitor (FSCM) allows the device to continue operating should the external oscillator or external clock fail. If an oscillator mode is selected, the FSCM can detect oscillator failure any time after the Oscillator Start-up Timer (OST) has expired. When an external clock mode is selected, the FSCM can detect failure as soon as the device is released from Reset.

FSCM is enabled by setting the FCMEN bit in the Configuration Words. The FSCM is applicable to external oscillator modes (LP, XT, HS) and external clock modes (ECH, ECM, ECL, EXTRC) and the Secondary Oscillator (SOSC).

FIGURE 5-9: FSCM BLOCK DIAGRAM



5.5.1 FAIL-SAFE DETECTION

The FSCM module detects a failed oscillator by monitoring falling clock edges and using LFINTOSC as a time base. See Figure 5-9. Detection of a failed oscillator will take 32 to 96 cycles of the LFINTOSC. Figure 5-10 shows a timing diagram of the FSCM module.

5.5.2 FAIL-SAFE OPERATION

When the external clock fails, the FSCM switches the CPU clock to an internal clock source and sets the OSFIF bit of the PIR2 register. The internal clock source is determined by the IRCF<3:0> bits in the OSCCON register.

When the OSFIF bit is set, an interrupt will be generated, if the OSFIE bit in the PIE2 register is enabled. The user's firmware in the Interrupt Service Routine (ISR) can then take steps to mitigate the problems that may arise from the failed clock.

The system clock will continue to be sourced from the internal clock source until the fail-safe condition has been cleared, see **Section 5.5.3 "Fail-Safe Condition Clearing"**.

5.5.3 FAIL-SAFE CONDITION CLEARING

When a Fail-Safe condition exists, the user must take the following actions to clear the condition before returning to normal operation with the external source.

The next sections describe how to clear the Fail-Safe condition for specific clock selections (FOSC bits) and clock switching modes (SCS bit settings).

5.5.3.1 External Oscillator with SCS<1:0> = 00

When a Fail-Safe condition occurs with the FOSC bits selecting external oscillator (FOSC<2:0> = HS, XT, LP) and the clock switch has been selected to run from the FOSC selection (SCS<1:0> = 00), the condition is cleared by performing the following procedure.

When SCS<1:0> = 00 (Running from FOSC selection)

SCS<1:0> = 1x:

Change the SCS bits in the OSCCON register to select the internal oscillator block. This resets the OST timer and allows it to operate again.

OSFIF = 0:

Clear the OSFIF bit in the PIR2 register.

SCS<1:0> = 00:

Change the SCS bits in the OSCCON register to select the FOSC Configuration Word clock selection. This will start the OST. The CPU will continue to operate from the internal oscillator until the OST count is reached. When OST expires, the clock module will switch to the external oscillator and the Fail-Safe condition will be cleared.

If the Fail-Safe condition still exists, the OSFIF bit will again be set by hardware.

5.5.3.2 External Clock with SCS<1:0> = 00

When a Fail-Safe condition occurs with the FOSC bits selecting external clock (FOSC<2:0> = ECH, ECM, ECL, EXTRC) and the clock switch has selected to run from the FOSC selection (SCS<1:0> = 00), the condition is cleared by performing the following procedure.

When SCS<1:0> = 00 (Running from FOSC selection)

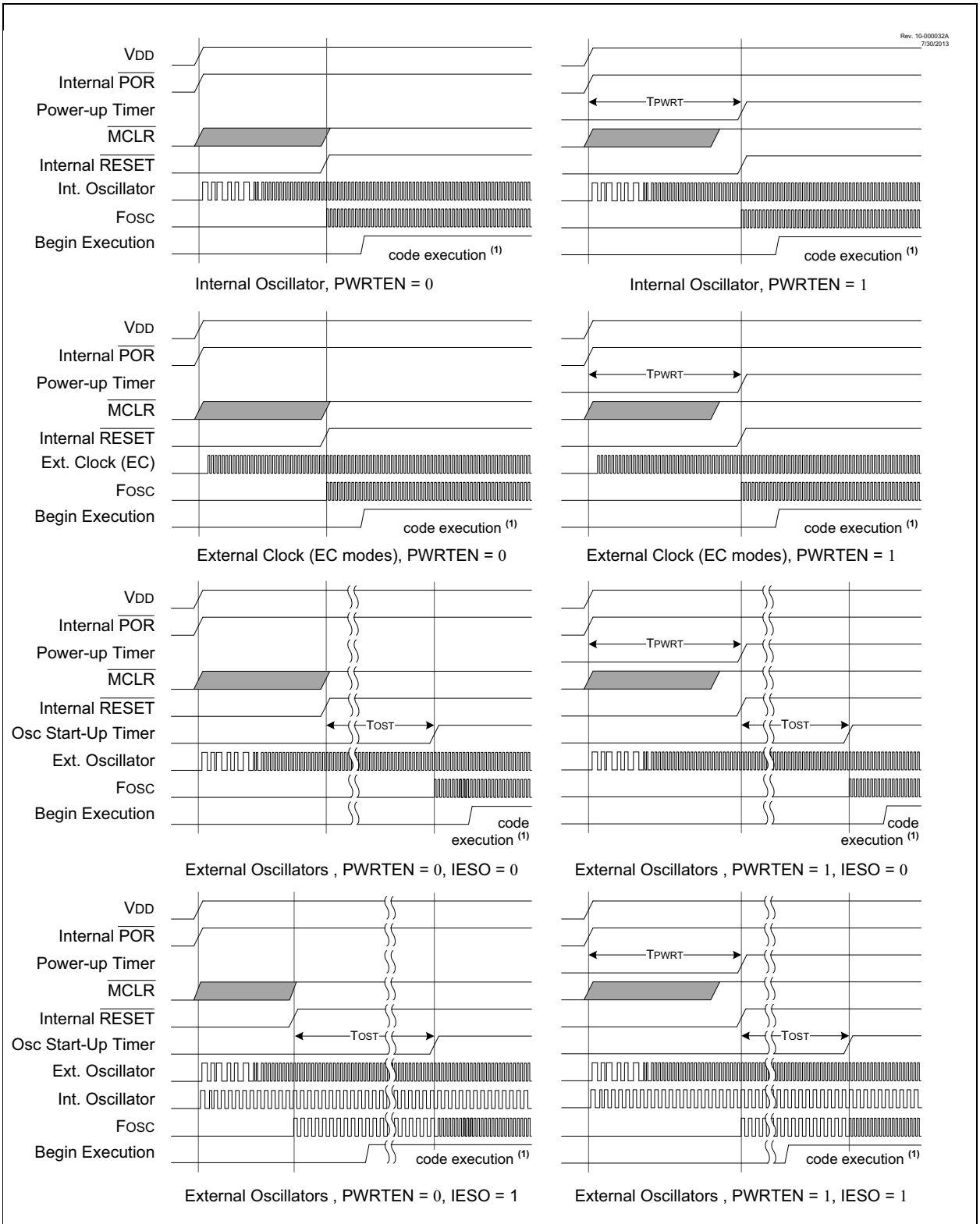
SCS<1:0> = 1x:

Change the SCS bits in the OSCCON register to select the internal oscillator block. This resets the OST timer and allows it to operate again.

OSFIF = 0:

Clear the OSFIF bit in the PIR2 register.

FIGURE 6-3: RESET START-UP SEQUENCE



Note 1: Code execution begins 10 FOSC cycles after the FOSC clock is released.

11.8 Register Definitions: PORTC

REGISTER 11-12: PORTC: PORTC REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **RC<7:0>**: PORTC General Purpose I/O Pin bits
1 = Port pin is $\geq$ VIH
0 = Port pin is $\leq$ VIL

REGISTER 11-13: TRISC: PORTC TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **TRISC<7:0>:** PORTC Tri-State Control bits
1 = PORTC pin configured as an input (tri-stated)
0 = PORTC pin configured as an output

REGISTER 11-14: LATC: PORTC DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **LATC<7:0>**: PORTC Output Latch Value bits(1)

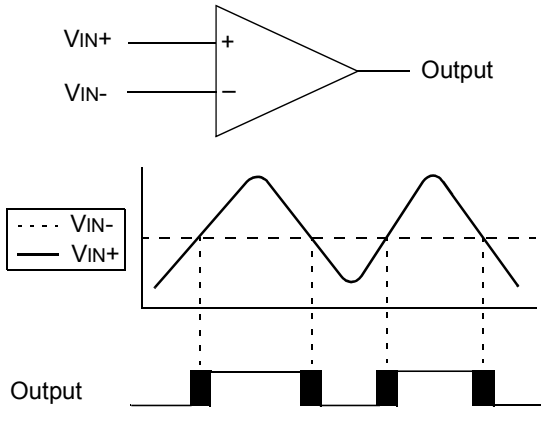
Note 1: Writes to PORTC are actually written to corresponding LATC register. Reads from PORTC register is return of actual I/O pin values.

TABLE 14-2: SUMMARY OF REGISTERS ASSOCIATED WITH THE TEMPERATURE INDICATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR>1:0>		ADFVR<1:0>		125

Legend: Shaded cells are unused by the temperature indicator module.

FIGURE 17-2: SINGLE COMPARATOR



Note: The black areas of the output of the comparator represents the uncertainty due to input offsets and response time.

17.2 Comparator Control

Each comparator has two control registers: CMxCON0 and CMxCON1.

The CMxCON0 registers (see Register 17-1) contain Control and Status bits for the following:

- Enable
- Output selection
- Output polarity
- Speed/Power selection
- Hysteresis enable
- Output synchronization

The CMxCON1 registers (see Register 17-2) contain Control bits for the following:

- Interrupt enable
- Interrupt edge polarity
- Positive input channel selection
- Negative input channel selection

17.2.1 COMPARATOR ENABLE

Setting the CxON bit of the CMxCON0 register enables the comparator for operation. Clearing the CxON bit disables the comparator resulting in minimum current consumption.

17.2.2 COMPARATOR POSITIVE INPUT SELECTION

Configuring the CxPCH<1:0> bits of the CMxCON1 register directs an internal voltage reference or an analog pin to the non-inverting input of the comparator:

- CxIN+ analog pin
- DAC1_output
- FVR_buffer2
- VSS

See **Section 13.0 "Fixed Voltage Reference (FVR)"** for more information on the Fixed Voltage Reference module.

See **Section 16.0 "5-Bit Digital-to-Analog Converter (DAC) Module"** for more information on the DAC input signal.

Any time the comparator is disabled (CxON = 0), all comparator inputs are disabled.

17.2.3 COMPARATOR NEGATIVE INPUT SELECTION

The CxNCH<2:0> bits of the CMxCON0 register direct one of the input sources to the comparator inverting input.

Note: To use CxIN+ and CxINx- pins as analog input, the appropriate bits must be set in the ANSEL register and the corresponding TRIS bits must also be set to disable the output drivers.

17.2.4 COMPARATOR OUTPUT SELECTION

The output of the comparator can be monitored by reading either the CxOUT bit of the CMxCON0 register or the MCxOUT bit of the CMOUT register. In order to make the output available for an external connection, the following conditions must be true:

- CxOE bit of the CMxCON0 register must be set
- Corresponding TRIS bit must be cleared
- CxON bit of the CMxCON0 register must be set

The synchronous comparator output signal (CxOUT_sync) is available to the following peripheral(s):

- Configurable Logic Cell (CLC)
- Analog-to-Digital Converter (ADC)
- Timer1

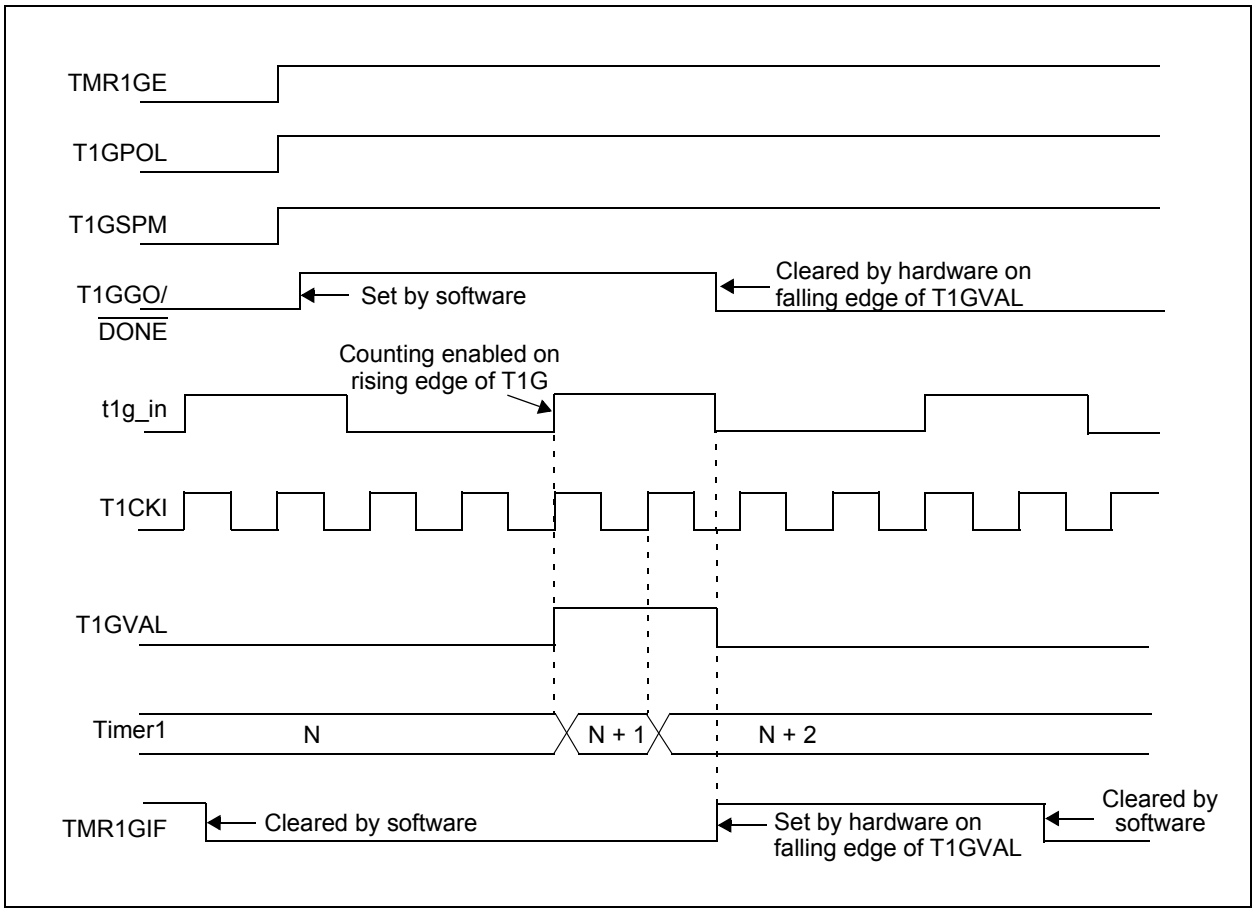
The asynchronous comparator output signal (CxOUT_async) is available to the following peripheral(s):

- Complementary Waveform Generator (CWG)

Note 1: The CxOE bit of the CMxCON0 register overrides the PORT data latch. Setting the CxON bit of the CMxCON0 register has no impact on the port override.

2: The internal output of the comparator is latched with each instruction cycle. Unless otherwise specified, external outputs are not latched.

FIGURE 19-5: TIMER1 GATE SINGLE-PULSE MODE



21.2 SPI Mode Overview

The Serial Peripheral Interface (SPI) bus is a synchronous serial data communication bus that operates in Full-Duplex mode. Devices communicate in a master/slave environment where the master device initiates the communication. A slave device is controlled through a Chip Select known as Slave Select.

The SPI bus specifies four signal connections:

- Serial Clock (SCKx)
- Serial Data Out (SDOx)
- Serial Data In (SDIx)
- Slave Select ($\overline{SS}$x)

Figure 21-1 shows the block diagram of the MSSP module when operating in SPI mode.

The SPI bus operates with a single master device and one or more slave devices. When multiple slave devices are used, an independent Slave Select connection is required from the master device to each slave device.

Figure 21-4 shows a typical connection between a master device and multiple slave devices.

The master selects only one slave at a time. Most slave devices have tri-state outputs so their output signal appears disconnected from the bus when they are not selected.

Transmissions involve two shift registers, eight bits in size, one in the master and one in the slave. With either the master or the slave device, data is always shifted out one bit at a time, with the Most Significant bit (MSb) shifted out first. At the same time, a new Least Significant bit (LSb) is shifted into the same register.

Figure 21-5 shows a typical connection between two processors configured as master and slave devices.

Data is shifted out of both shift registers on the programmed clock edge and latched on the opposite edge of the clock.

The master device transmits information out on its SDOx output pin which is connected to, and received by, the slave's SDIx input pin. The slave device transmits information out on its SDOx output pin, which is connected to, and received by, the master's SDIx input pin.

To begin communication, the master device first sends out the clock signal. Both the master and the slave devices should be configured for the same clock polarity.

The master device starts a transmission by sending out the MSb from its shift register. The slave device reads this bit from that same line and saves it into the LSb position of its shift register.

During each SPI clock cycle, a full-duplex data transmission occurs. This means that while the master device is sending out the MSb from its shift register (on its SDOx pin) and the slave device is reading this bit and saving it as the LSb of its shift register, that the slave device is also sending out the MSb from its shift register (on its SDOx pin) and the master device is reading this bit and saving it as the LSb of its shift register.

After eight bits have been shifted out, the master and slave have exchanged register values.

If there is more data to exchange, the shift registers are loaded with new data and the process repeats itself.

Whether the data is meaningful or not (dummy data), depends on the application software. This leads to three scenarios for data transmission:

- Master sends useful data and slave sends dummy data.
- Master sends useful data and slave sends useful data.
- Master sends dummy data and slave sends useful data.

Transmissions may involve any number of clock cycles. When there is no more data to be transmitted, the master stops sending the clock signal and it deselects the slave.

Every slave device connected to the bus that has not been selected through its slave select line must disregard the clock and transmission signals and must not transmit out any data of its own.

FIGURE 21-9: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 0)

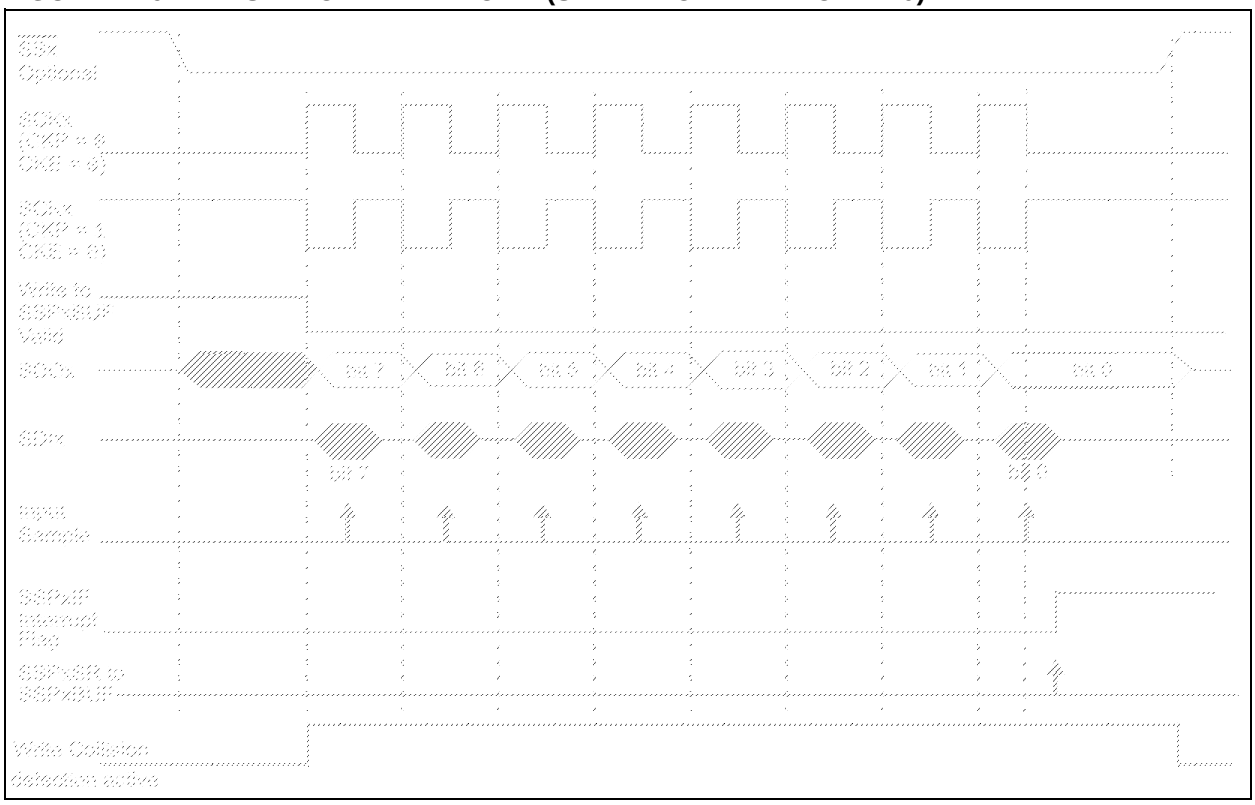
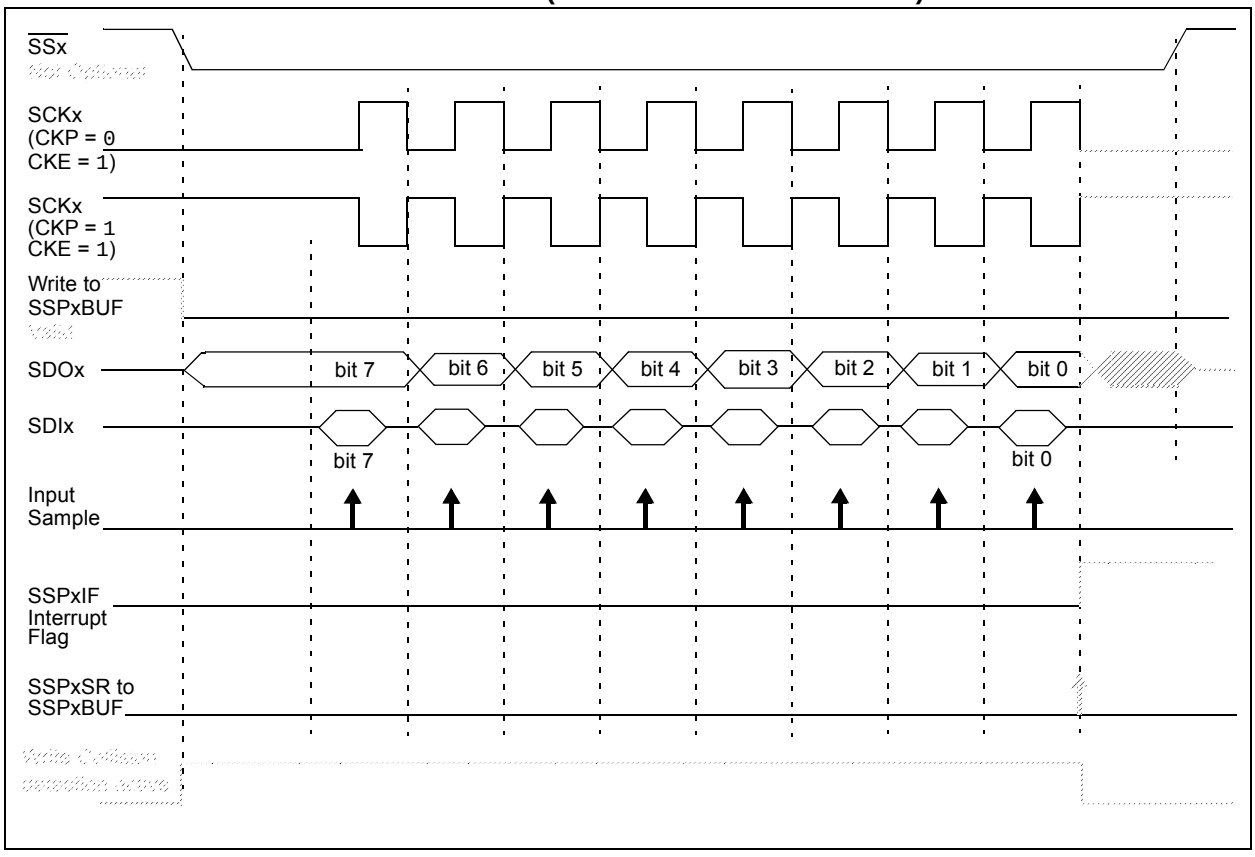


FIGURE 21-10: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 1)



21.6.7 I²C MASTER MODE RECEPTION

Master mode reception (Figure 21-29) is enabled by programming the Receive Enable bit, RCEN bit of the SSPxCON2 register.

Note:	The MSSPx module must be in an Idle state before the RCEN bit is set or the RCEN bit will be disregarded.

The Baud Rate Generator begins counting and on each rollover, the state of the SCLx pin changes (high-to-low/low-to-high) and data is shifted into the SSPxSR. After the falling edge of the eighth clock, the receive enable flag is automatically cleared, the contents of the SSPxSR are loaded into the SSPxBUF, the BF flag bit is set, the SSPxIF flag bit is set and the Baud Rate Generator is suspended from counting, holding SCLx low. The MSSP is now in Idle state awaiting the next command. When the buffer is read by the CPU, the BF flag bit is automatically cleared. The user can then send an Acknowledge bit at the end of reception by setting the Acknowledge Sequence Enable, ACKEN bit of the SSPxCON2 register.

21.6.7.1 BF Status Flag

In receive operation, the BF bit is set when an address or data byte is loaded into SSPxBUF from SSPxSR. It is cleared when the SSPxBUF register is read.

21.6.7.2 SSPOV Status Flag

In receive operation, the SSPOV bit is set when eight bits are received into the SSPxSR and the BF flag bit is already set from a previous reception.

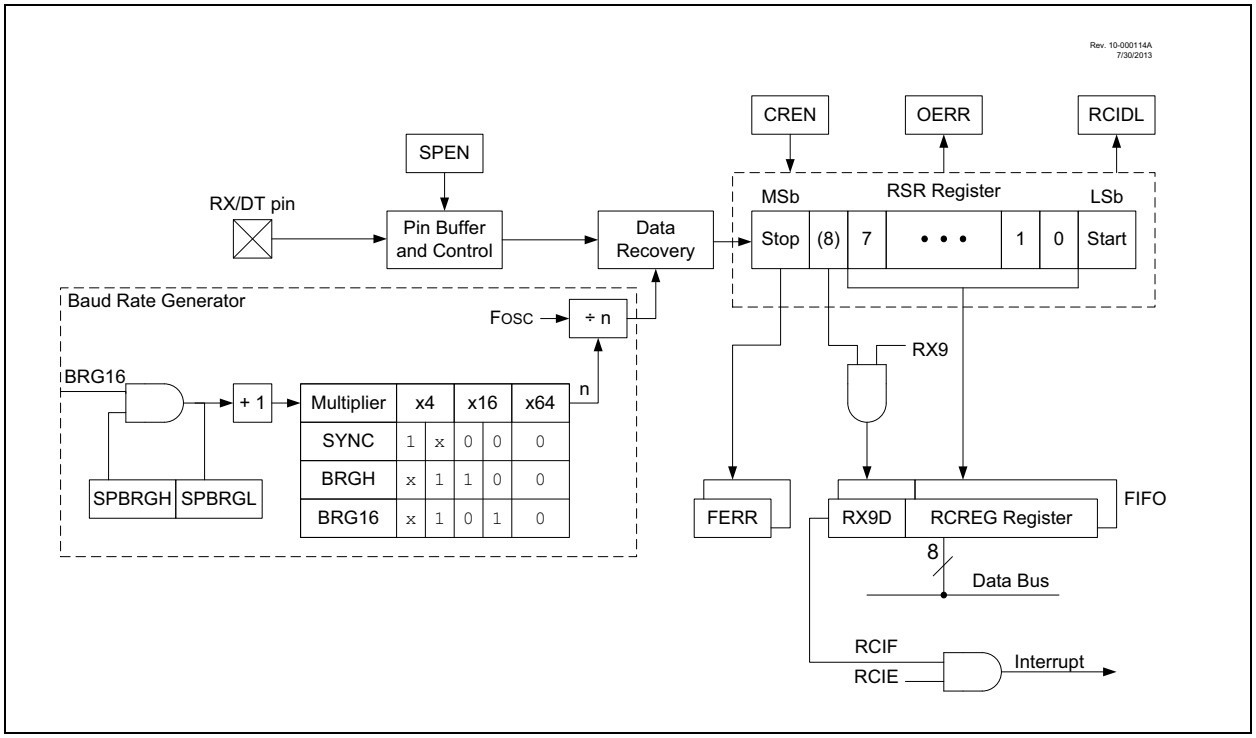
21.6.7.3 WCOL Status Flag

If the user writes the SSPxBUF when a receive is already in progress (i.e., SSPxSR is still shifting in a data byte), the WCOL bit is set and the contents of the buffer are unchanged (the write does not occur).

21.6.7.4 Typical Receive Sequence:

1. The user generates a Start condition by setting the SEN bit of the SSPxCON2 register.
2. SSPxIF is set by hardware on completion of the Start.
3. SSPxIF is cleared by software.
4. User writes SSPxBUF with the slave address to transmit and the R/$\overline{W}$ bit set.
5. Address is shifted out the SDAx pin until all eight bits are transmitted. Transmission begins as soon as SSPxBUF is written to.
6. The MSSP module shifts in the $\overline{ACK}$ bit from the slave device and writes its value into the ACKSTAT bit of the SSPxCON2 register.
7. The MSSP module generates an interrupt at the end of the ninth clock cycle by setting the SSPxIF bit.
8. User sets the RCEN bit of the SSPxCON2 register and the master clocks in a byte from the slave.
9. After the eighth falling edge of SCLx, SSPxIF and BF are set.
10. Master clears SSPxIF and reads the received byte from SSPxBUF, clears BF.
11. Master sets $\overline{ACK}$ value sent to slave in ACKDT bit of the SSPxCON2 register and initiates the $\overline{ACK}$ by setting the ACKEN bit.
12. Masters $\overline{ACK}$ is clocked out to the slave and SSPxIF is set.
13. User clears SSPxIF.
14. Steps 8-13 are repeated for each received byte from the slave.
15. Master sends a not $\overline{ACK}$ or Stop to end communication.

FIGURE 22-2: EUSART RECEIVE BLOCK DIAGRAM



The operation of the EUSART module is controlled through three registers:

- Transmit Status and Control (TXSTA)
- Receive Status and Control (RCSTA)
- Baud Rate Control (BAUDCON)

These registers are detailed in Register 22-1, Register 22-2 and Register 22-3, respectively.

When the receiver or transmitter section is not enabled then the corresponding RX or TX pin may be used for general purpose input and output.

FIGURE 28-1: GENERAL FORMAT FOR INSTRUCTIONS

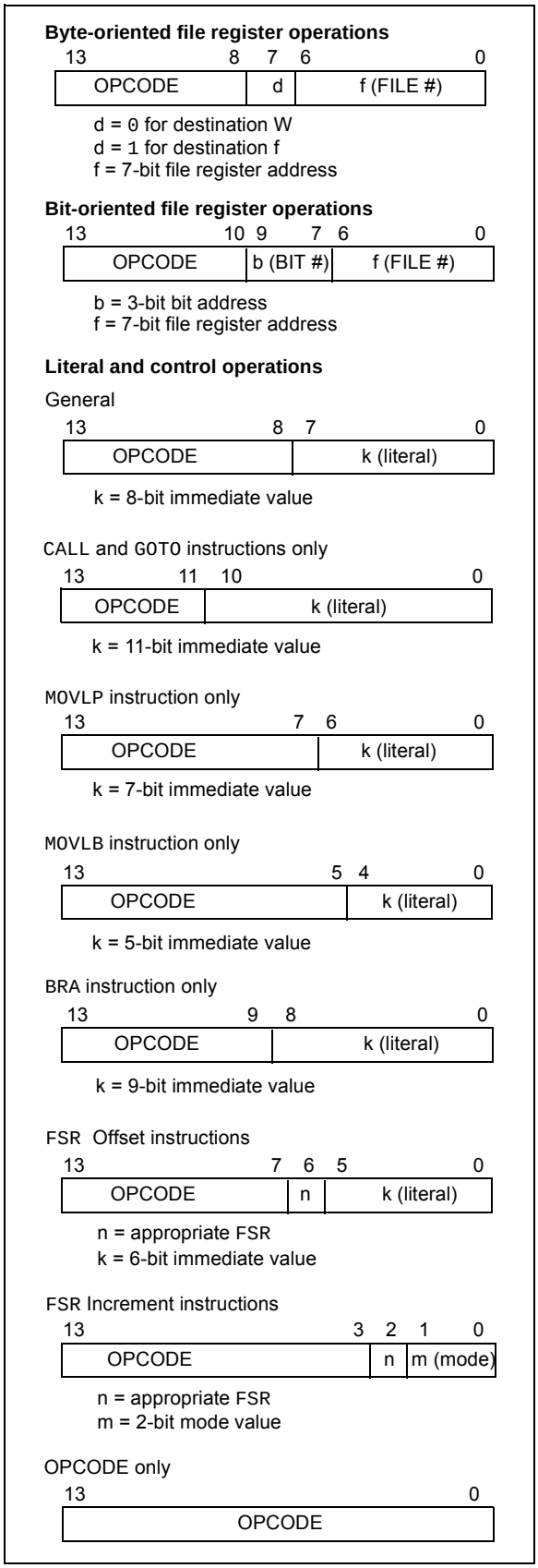


TABLE 29-2: SUPPLY CURRENT (I_{DD})(1,2)

PIC16LF1508/9		Standard Operating Conditions (unless otherwise stated)					
PIC16F1508/9							
Param. No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						V_{DD}	Note
D010		—	8	20	µA	1.8	F_{OSC} = 32 kHz, LP Oscillator, -40°C ≤ T_A ≤ +85°C
		—	10	25	µA	3.0	
D010		—	15	31	µA	2.3	F_{OSC} = 32 kHz, LP Oscillator, -40°C ≤ T_A ≤ +85°C
		—	17	33	µA	3.0	
		—	21	39	µA	5.0	
D011		—	60	100	µA	1.8	F_{OSC} = 1 MHz, XT Oscillator
		—	100	180	µA	3.0	
D011		—	100	180	µA	2.3	F_{OSC} = 1 MHz, XT Oscillator
		—	130	220	µA	3.0	
		—	170	280	µA	5.0	
D012		—	140	240	µA	1.8	F_{OSC} = 4 MHz, XT Oscillator
		—	250	360	µA	3.0	
D012		—	210	320	µA	2.3	F_{OSC} = 4 MHz, XT Oscillator
		—	280	410	µA	3.0	
		—	340	500	µA	5.0	
D013		—	30	65	µA	1.8	F_{OSC} = 1 MHz, External Clock (ECM), Medium Power mode
		—	55	100	µA	3.0	
D013		—	65	110	µA	2.3	F_{OSC} = 1 MHz, External Clock (ECM), Medium Power mode
		—	85	140	µA	3.0	
		—	115	190	µA	5.0	
D014		—	115	190	µA	1.8	F_{OSC} = 4 MHz, External Clock (ECM), Medium Power mode
		—	210	310	µA	3.0	
D014		—	180	270	µA	2.3	F_{OSC} = 4 MHz, External Clock (ECM), Medium Power mode
		—	240	365	µA	3.0	
		—	295	460	µA	5.0	
D015		—	3.2	12	µA	1.8	F_{OSC} = 31 kHz, LFINTOSC, -40°C ≤ T_A ≤ +85°C
		—	5.4	20	µA	3.0	
D015		—	13	28	µA	2.3	F_{OSC} = 31 kHz, LFINTOSC, -40°C ≤ T_A ≤ +85°C
		—	15	30	µA	3.0	
		—	17	36	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all I_{DD} measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{SS}; $\overline{MCLR}$ = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: For RC oscillator configurations, current through R_{EXT} is not included. The current through the resistor can be extended by the formula IR = $V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in kΩ.

TABLE 29-2: SUPPLY CURRENT (I_{DD})(1,2) (CONTINUED)

PIC16LF1508/9		Standard Operating Conditions (unless otherwise stated)					
PIC16F1508/9							
Param. No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						V_{DD}	Note
D019B		—	6	16	μA	1.8	F_{OSC} = 32 kHz, External Clock (ECL), Low-Power mode
		—	8	22	μA	3.0	
D019B		—	13	28	μA	2.3	F_{OSC} = 32 kHz, External Clock (ECL), Low-Power mode
		—	15	31	μA	3.0	
		—	16	36	μA	5.0	
D019C		—	19	35	μA	1.8	F_{OSC} = 500 kHz, External Clock (ECL), Low-Power mode
		—	32	55	μA	3.0	
D019C		—	31	52	μA	2.3	F_{OSC} = 500 kHz, External Clock (ECL), Low-Power mode
		—	38	65	μA	3.0	
		—	44	74	μA	5.0	
D020		—	140	210	μA	1.8	F_{OSC} = 4 MHz, EXTRC (**Note 3**)
		—	250	330	μA	3.0	
D020		—	210	290	μA	2.3	F_{OSC} = 4 MHz, EXTRC (**Note 3**)
		—	280	380	μA	3.0	
		—	350	470	μA	5.0	
D021		—	1135	1700	μA	3.0	F_{OSC} = 20 MHz, HS Oscillator
D021		—	1170	1800	μA	3.0	F_{OSC} = 20 MHz, HS Oscillator
		—	1555	2300	μA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all I_{DD} measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{SS}; $\overline{MCLR}$ = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: For RC oscillator configurations, current through R_{EXT} is not included. The current through the resistor can be extended by the formula IR = $V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in kΩ.

TABLE 29-4: I/O PORTS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O PORT:					
D030		with TTL buffer	—	—	0.8	V	4.5V ≤ VDD ≤ 5.5V
D030A			—	—	0.15 VDD	V	1.8V ≤ VDD ≤ 4.5V
D031		with Schmitt Trigger buffer	—	—	0.2 VDD	V	2.0V ≤ VDD ≤ 5.5V
		with I^2C levels	—	—	0.3 VDD	V	
		with SMbus levels	—	—	0.8	V	2.7V ≤ VDD ≤ 5.5V
D032		$\overline{MCLR}$, OSC1 (EXTRC mode)	—	—	0.2 VDD	V	**(Note 1)**
D033		OSC1 (HS mode)	—	—	0.3 VDD	V	
	VIH	**Input High Voltage**					
		I/O PORT:					
D040		with TTL buffer	2.0	—	—	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25 VDD + 0.8	—	—	V	1.8V ≤ VDD ≤ 4.5V
D041		with Schmitt Trigger buffer	0.8 VDD	—	—	V	2.0V ≤ VDD ≤ 5.5V
		with I^2C levels	0.7 VDD	—	—	V	
		with SMbus levels	2.1	—	—	V	2.7V ≤ VDD ≤ 5.5V
D042		$\overline{MCLR}$	0.8 VDD	—	—	V	
D043A		OSC1 (HS mode)	0.7 VDD	—	—	V	
D043B		OSC1 (EXTRC mode)	0.9 VDD	—	—	V	VDD > 2.0V **(Note 1)**
	IIL	**Input Leakage Current(2)**					
D060		I/O Ports	—	± 5	± 125	nA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, 85°C
			—	± 5	± 1000	nA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, 125°C
D061		$\overline{MCLR}$(3)	—	± 50	± 200	nA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, 85°C
	IPUR	**Weak Pull-up Current**					
D070*			25	100	200	µA	VDD = 3.3V, VPIN = VSS
			25	140	300	µA	VDD = 5.0V, VPIN = VSS
	VOL	**Output Low Voltage**					
D080		I/O Ports	—	—	0.6	V	IOL = 8 mA, VDD = 5V IOL = 6 mA, VDD = 3.3V IOL = 1.8 mA, VDD = 1.8V
	VOH	**Output High Voltage**					
D090		I/O Ports	VDD - 0.7	—	—	V	IOH = 3.5 mA, VDD = 5V IOH = 3 mA, VDD = 3.3V IOH = 1 mA, VDD = 1.8V
D101*	COSC2	**Capacitive Loading Specifications on Output Pins**					
		OSC2 pin	—	—	15	pF	In XT, HS, LP modes when external clock is used to drive OSC1
D101A*	CIO	All I/O pins	—	—	50	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In EXTRC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended to use an external clock in EXTRC mode.

2: Negative current is defined as current sourced by the pin.

3: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

FIGURE 29-10: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

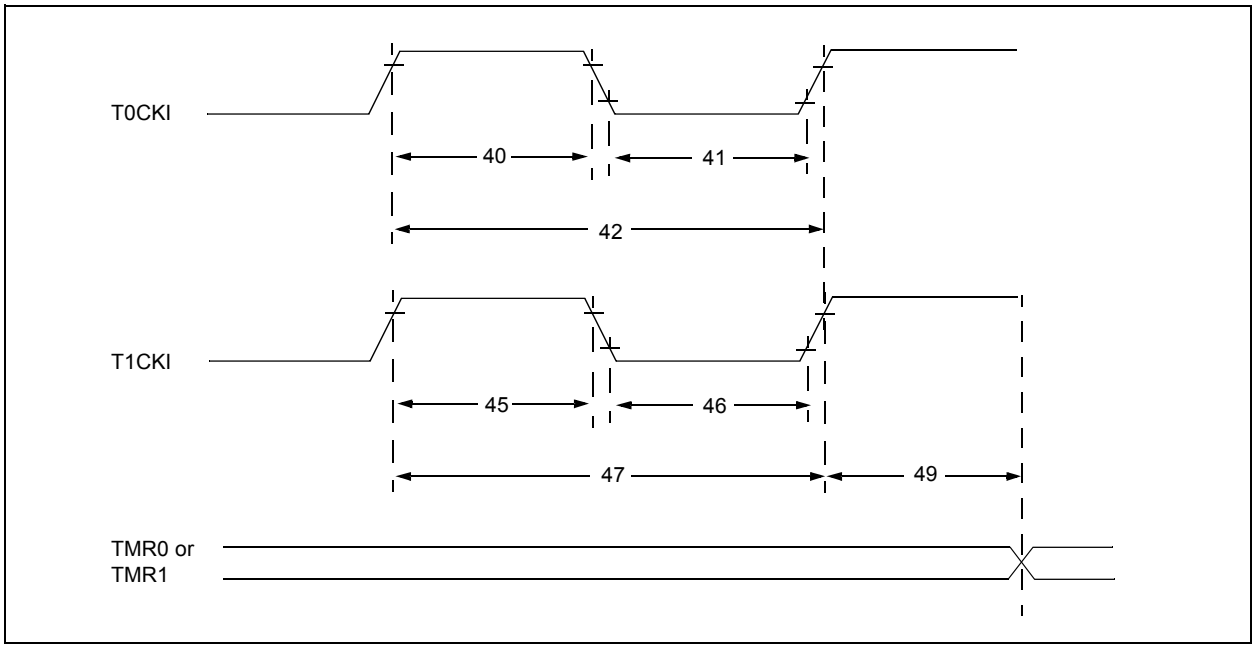


TABLE 29-11: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

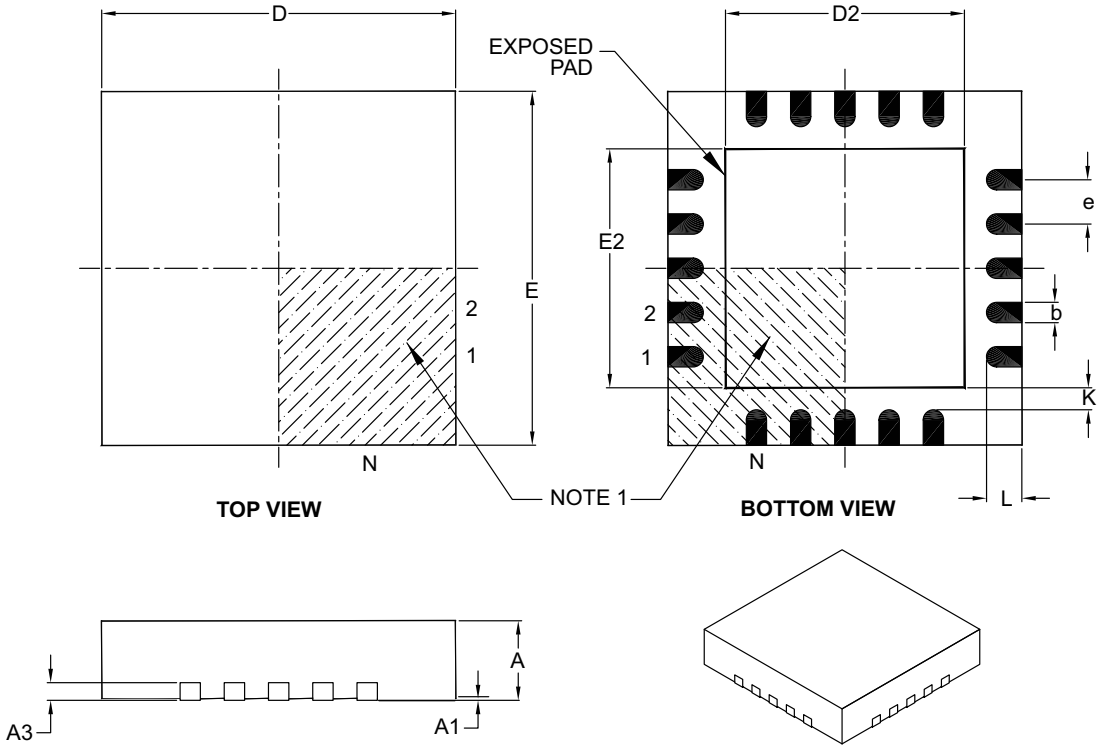
Standard Operating Conditions (unless otherwise stated)								
Param. No.	**Sym.**	**Characteristic**		**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
40*	TT0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
41*	TT0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
42*	TT0P	T0CKI Period		Greater of: 20 or $\frac{T_{CY} + 40}{N}$	—	—	ns	N = prescale value
45*	TT1H	T1CKI High Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
46*	TT1L	T1CKI Low Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
47*	TT1P	T1CKI Input Period	Synchronous	Greater of: 30 or $\frac{T_{CY} + 40}{N}$	—	—	ns	N = prescale value
			Asynchronous	60	—	—	ns	
48	FT1	Secondary Oscillator Input Frequency Range (Oscillator enabled by setting bit T1OSCEN)		32.4	32.768	33.1	kHz	
49*	TCKEZTMR1	Delay from External Clock Edge to Timer Increment		2 TOSC	—	7 TOSC	—	Timers in Sync mode

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

20-Lead Plastic Quad Flat, No Lead Package (ML) – 4x4x0.9 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		4.00 BSC	
Exposed Pad Width	E2	2.60	2.70	2.80
Overall Length	D		4.00 BSC	
Exposed Pad Length	D2	2.60	2.70	2.80
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

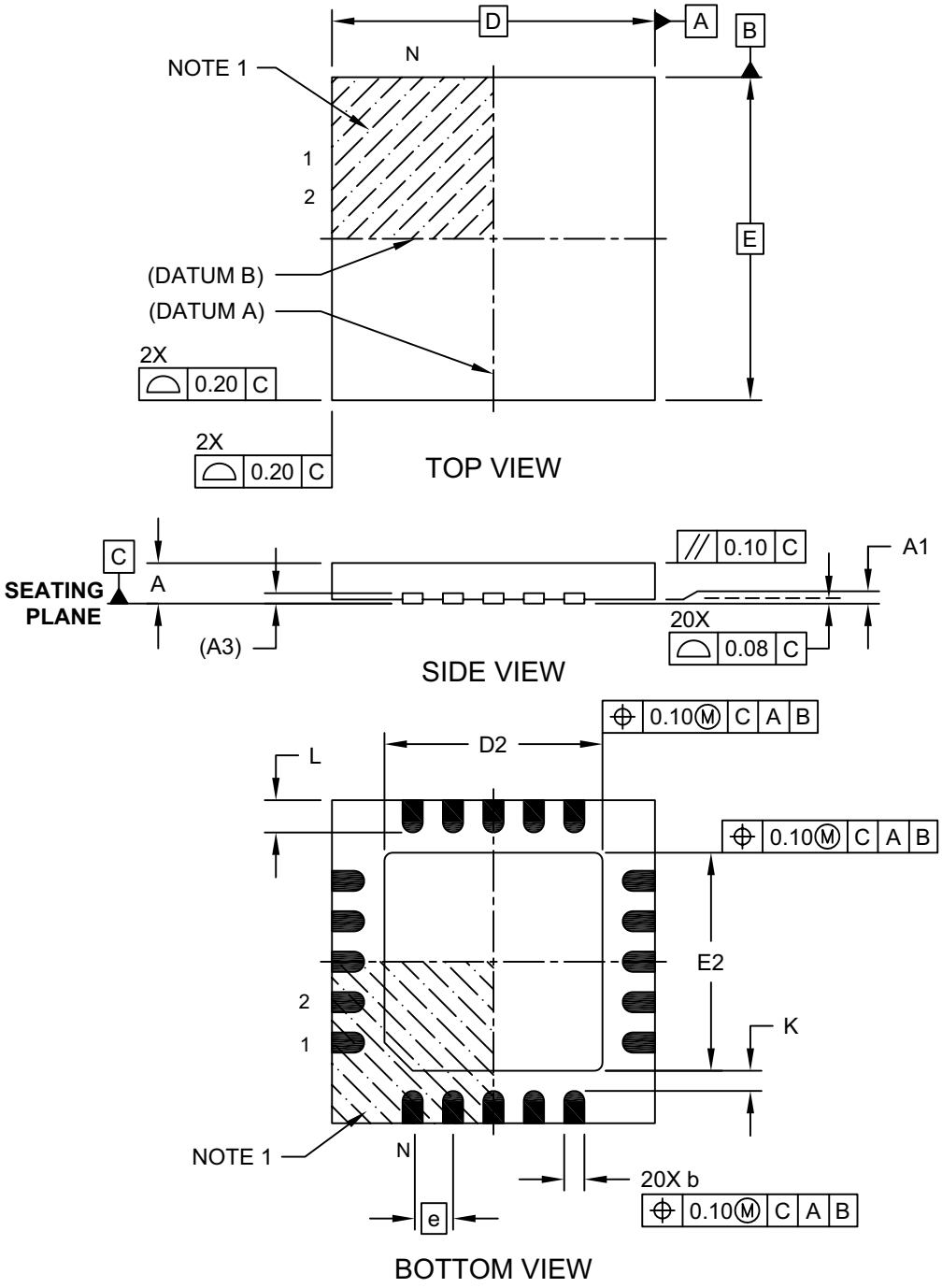
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-126B

20-Lead Ultra Thin Plastic Quad Flat, No Lead Package (GZ) - 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-255A Sheet 1 of 2